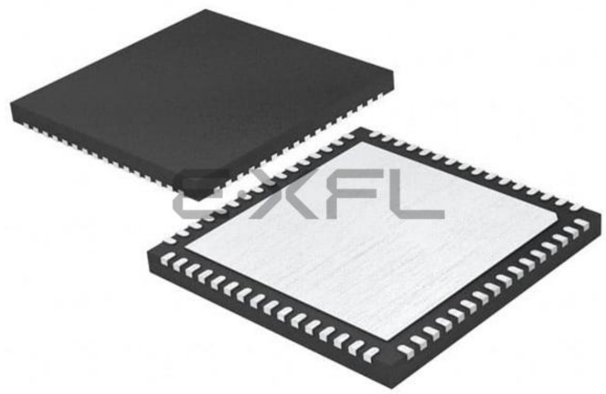
E·XFL

Microchip Technology - PIC32MX330F064H-I/RG Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx330f064h-i-rg

TABLE 4: PIN NAMES FOR 100-PIN DEVICES

100-PIN TQFP (TOP VIEW)(1,2,3)

PIC32MX330F064L
PIC32MX350F128L
PIC32MX350F256L
PIC32MX370F512L

100

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RG15	36	VSS
2	VDD	37	VDD
3	AN22/RPE5/PMD5/RE5	38	TCK/CTED2/RA1
4	AN23/PMD6/RE6	39	RPF13/RF13
5	AN27/PMD7/RE7	40	RPF12/RF12
6	RPC1/RC1	41	AN12/PMA11/RB12
7	RPC2/RC2	42	AN13/PMA10/RB13
8	RPC3/RC3	43	AN14/RPB14/CTED5/PMA1/RB14
9	RPC4/CTED7/RC4	44	AN15/RPB15/OCFB/CTED6/PMA0/RB15
10	AN16/C1IND/RPG6/SCK2/PMA5/RG6	45	VSS
11	AN17/C1INC/RPG7/PMA4/RG7	46	VDD
12	AN18/C2IND/RPG8/PMA3/RG8	47	RPD14/RD14
13	$\overline{\text{MCLR}}$	48	RPD15/RD15
14	AN19/C2INC/RPG9/PMA2/RG9	49	RPF4/PMA9/RF4
15	VSS	50	RPF5/PMA8/RF5
16	VDD	51	RPF3/RF3
17	TMS/CTED1/RA0	52	RPF2/RF2
18	RPE8/RE8	53	RPF8/RF8
19	RPE9/RE9	54	RPF7/RF7
20	AN5/C1INA/RPB5/RB5	55	RPF6/SCK1/INT0/RF6
21	AN4/C1INB/RB4	56	SDA1/RG3
22	PGED3/AN3/C2INA/RPB3/RB3	57	SCL1/RG2
23	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	58	SCL2/RA2
24	PGEC1/AN1/RPB1/CTED12/RB1	59	SDA2/RA3
25	PGED1/AN0/RPB0/RB0	60	TDI/CTED9/RA4
26	PGEC2/AN6/RPB6/RB6	61	TDO/RA5
27	PGED2/AN7/RPB7/CTED3/RB7	62	VDD
28	VREF-/CVREF-/PMA7/RA9	63	OSC1/CLKI/RC12
29	VREF+/CVREF+/PMA6/RA10	64	OSC2/CLKO/RC15
30	AVDD	65	VSS
31	AVSS	66	RPA14/RA14
32	AN8/RPB8/CTED10/RB8	67	RPA15/RA15
33	AN9/RPB9/CTED4/RB9	68	RPD8/RTCC/RD8
34	CVREFOUT/AN10/RPB10/CTED11PMA13/RB10	69	RPD9/RD9
35	AN11/PMA12/RB11	70	RPD10/PMCS2/RD10

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx), with the exception of RF6, can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: RPF6 (pin 55) and RPF7 (pin 54) are only remappable for input functions.

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
AN0	16	25	B14	I	Analog	Analog input channels.
AN1	15	24	A15	I	Analog	
AN2	14	23	B13	I	Analog	
AN3	13	22	A13	I	Analog	
AN4	12	21	B11	I	Analog	
AN5	11	20	A12	I	Analog	
AN6	17	26	A20	I	Analog	
AN7	18	27	B16	I	Analog	
AN8	21	32	A23	I	Analog	
AN9	22	33	B19	I	Analog	
AN10	23	34	A24	I	Analog	
AN11	24	35	B20	I	Analog	
AN12	27	41	B23	I	Analog	
AN13	28	42	A28	I	Analog	
AN14	29	43	B24	I	Analog	
AN15	30	44	A29	I	Analog	
AN16	4	10	A7	I	Analog	
AN17	5	11	B6	I	Analog	
AN18	6	12	A8	I	Analog	
AN19	8	14	A9	I	Analog	
AN20	62	98	A66	I	Analog	
AN21	64	100	A67	I	Analog	
AN22	1	3	B2	I	Analog	
AN23	2	4	A4	I	Analog	
AN24	49	76	A52	I	Analog	
AN25	50	77	B42	I	Analog	
AN26	51	78	A53	I	Analog	
AN27	3	5	B3	I	Analog	
CLKI	39	63	B34	I	ST/CMOS	External clock source input. Always associated with OSC1 pin function.
CLKO	40	64	A42	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with the OSC2 pin function.
OSC1	39	63	B34	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	40	64	A42	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
SOSCI	47	73	A47	I	ST/CMOS	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	48	74	B40	O	—	32.768 kHz low-power oscillator crystal output.

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
P = Power
I = Input

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

© 2012-2016 Microchip Technology Inc.

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- C_{IN} = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- C_{OUT} = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}]\} + \textit{estimated oscillator PCB stray capacitance}$$

$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5]\} + 2.5\ pF$$

$$= \{([20][20]) / [40]\} + 2.5$$

$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 13 pF in this example for Primary Oscillator crystals “C1” and “C2”.

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

- Select a crystal with a lower “minimum” power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing “ESR” rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

> **Note:** Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit “C” in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~V_{DD}-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

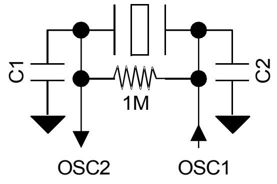
- AN588 *“PICmicro® Microcontroller Oscillator Design Guide”*
- AN826 *“Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices”*
- AN849 *“Basic PICmicro® Oscillator Design”*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS

Circuit A

Typical XT

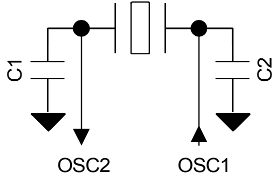
(4-10 MHz)



Circuit B

Typical HS

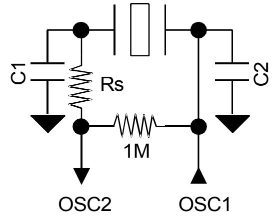
(10-25 MHz)



Circuit C

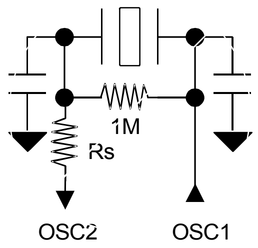
Typical XT/HS

(4-25 MHz)



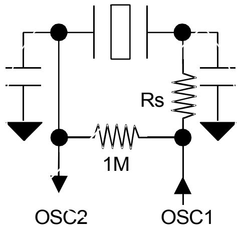
Circuit D

Not Recommended



Circuit E

Not Recommended



© 2012-2016 Microchip Technology Inc.

FIGURE 2-8: LOW-COST CONTROLLERLESS (LCC) GRAPHICS APPLICATION WITH PROJECTED CAPACITIVE TOUCH

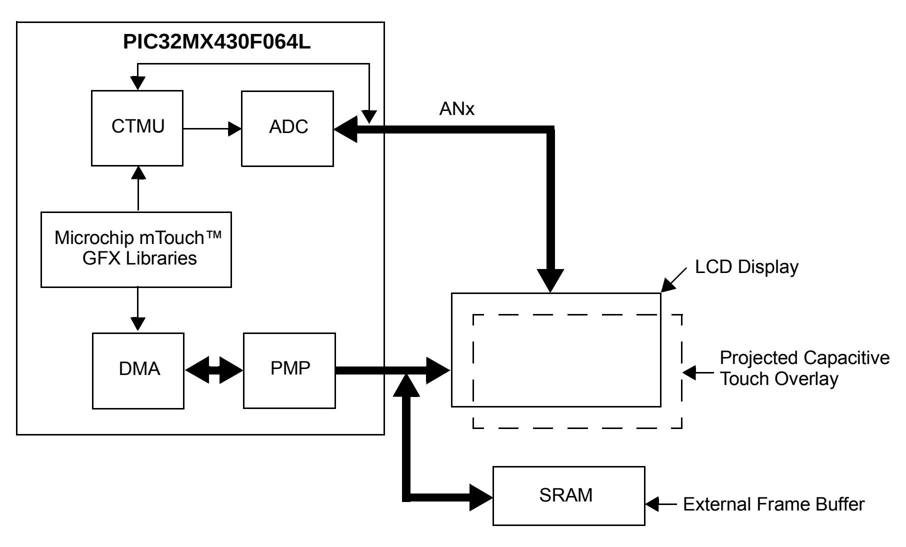
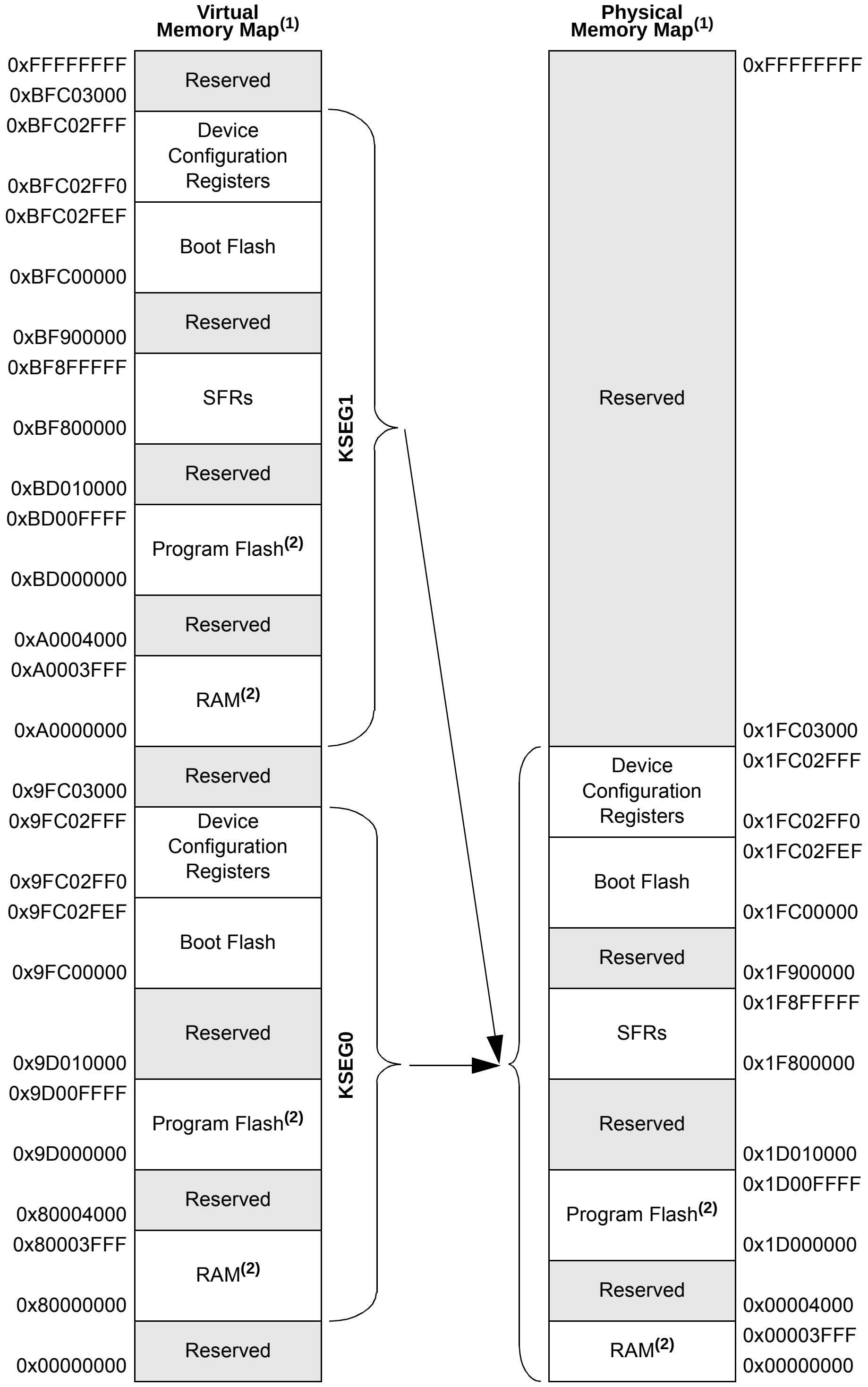


FIGURE 4-1: MEMORY MAP FOR DEVICES WITH 64 KB OF PROGRAM MEMORY



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

© 2012-2016 Microchip Technology Inc.

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 6. "Oscillator Configuration"** (DS60001112), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX330/350/370/430/450/470 oscillator system has the following modules and features:

- A Total of four external and internal oscillator options as clock sources
- On-Chip PLL with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-Chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Dedicated On-Chip PLL for USB peripheral

A block diagram of the oscillator system is provided in Figure 8-1.

© 2012-2016 Microchip Technology Inc.

9.0 PREFETCH CACHE

> **Note:** This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Prefetch Cache"** (DS60001119), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

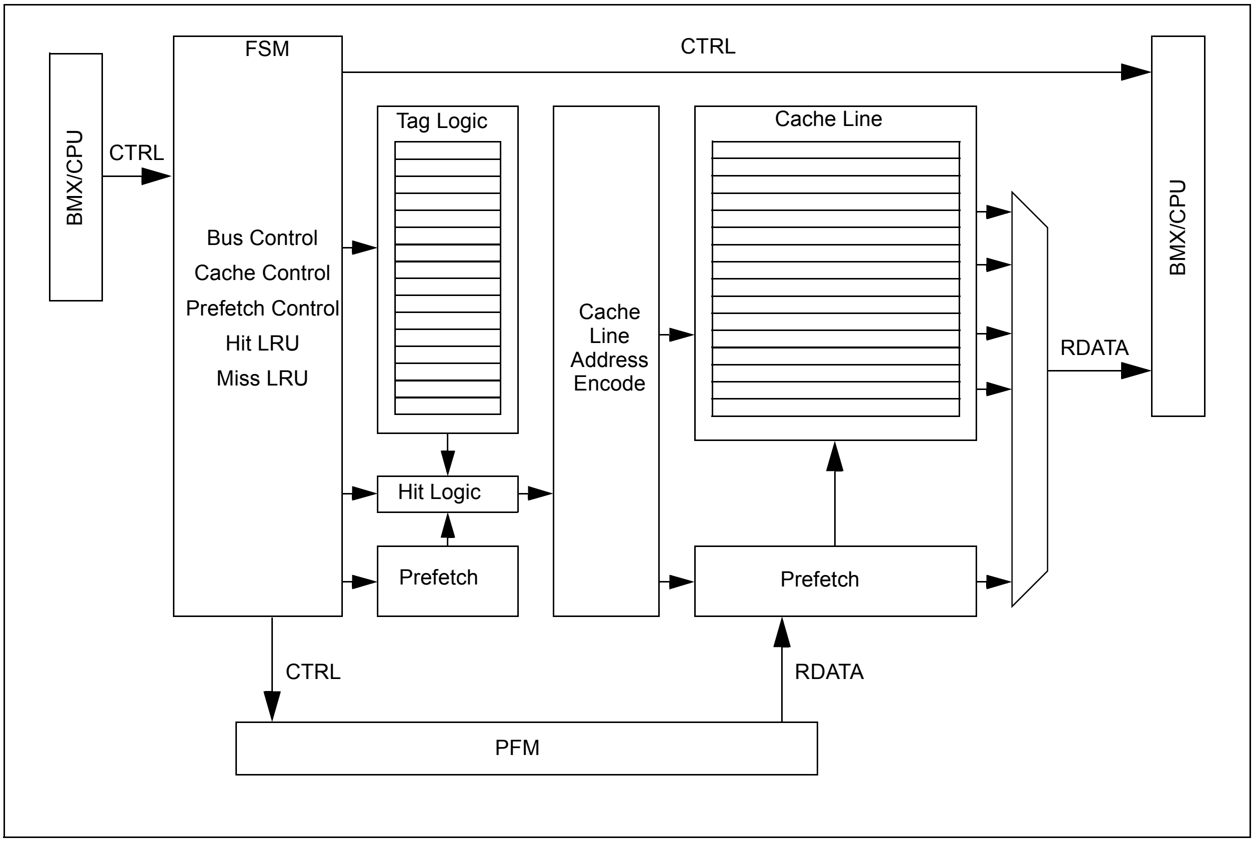
Prefetch cache increases performance for applications executing out of the cacheable program Flash memory regions by implementing instruction caching, constant data caching and instruction prefetching.

9.1 Features

- 16 fully associative lockable cache lines
- 16-byte cache lines
- Up to four cache lines allocated to data
- Two cache lines with address mask to hold repeated instructions
- Pseudo LRU replacement policy
- All cache lines are software writable
- 16-byte parallel memory fetch
- Predictive instruction prefetch

A simplified block diagram of the Prefetch Cache module is illustrated in Figure 9-1.

FIGURE 9-1: PREFETCH CACHE MODULE BLOCK DIAGRAM



REGISTER 9-4: CHEMSK: CACHE TAG MASK REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	LMASK<10:3>							
7:0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	LMASK<2:0>			—	—	—	—	—

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Write ‘0’; ignore read

bit 15-5 **LMASK<10:0>:** Line Mask bits

1 = Enables mask logic to force a match on the corresponding bit position in the LTAG<19:0> bits (CHETAG<23:4>) and the physical address.
0 = Only writeable for values of CHEIDX<3:0> bits (CHEACC<3:0>) equal to 0x0A and 0x0B.
Disables mask logic.

bit 4-0 **Unimplemented:** Write ‘0’; ignore read

REGISTER 9-5: CHEW0: CACHE WORD 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW0<31:24>							
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW0<23:16>							
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW0<15:8>							
7:0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	CHEW0<7:0>							

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-0 **CHEW0<31:0>:** Word 0 of the cache line selected by the CHEIDX<3:0> bits (CHEACC<3:0>)
Readable only if the device is not code-protected.

© 2012-2016 Microchip Technology Inc.

REGISTER 10-2: DMASTAT: DMA STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
	—	—	—	—	RDWR	DMACH<2:0>		

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-4 **Unimplemented:** Read as ‘0’

bit 3 **RDWR:** Read/Write Status bit
1 = Last DMA bus access was a read
0 = Last DMA bus access was a write

bit 2-0 **DMACH<2:0>:** DMA Channel bits
These bits contain the value of the most recent active DMA channel.

REGISTER 10-3: DMAADDR: DMA ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<31:24>							
23:16	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<23:16>							
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	DMAADDR<7:0>							

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-0 **DMAADDR<31:0>:** DMA Module Address bits
These bits contain the address of the most recent DMA access.

TABLE 12-4: PORTB REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6100	ANSELB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ANSELB15	ANSELB14	ANSELB13	ANSELB12	ANSELB11	ANSELB10	ANSELB9	ANSELB8	ANSELB7	ANSELB6	ANSELB5	ANSELB4	ANSELB3	ANSELB2	ANSELB1	ANSELB0	FFFF
6110	TRISB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	xxxx
6120	PORTB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
6130	LATB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
6140	ODCB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	xxxx
6150	CNPUB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	xxxx
6160	CNPDB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	xxxx
6170	CNCONB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6180	CNENB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	xxxx
6190	CNSTATB	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CN STATB15	CN STATB14	CN STATB13	CN STATB12	CN STATB11	CN STATB10	CN STATB9	CN STATB8	CN STATB7	CN STATB6	CN STATB5	CN STATB4	CN STATB3	CN STATB2	CN STATB1	CN STATB0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as ‘0’; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for more information.

TABLE 12-15: PORTG REGISTER MAP FOR PIC32MX330F064L, PIC32MX350F128L, PIC32MX350F256L, PIC32MX370F512L, PIC32MX430F064L, PIC32MX450F128L, PIC32MX450F256L, AND PIC32MX470F512L DEVICES ONLY

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6600	ANSELG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	ANSELG9	ANSELG8	ANSELG7	ANSELG6	—	—	—	—	—	—	01C0
6610	TRISG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TRISG15	TRISG14	TRISG13	TRISG12	—	—	TRISG9	TRISG8	TRISG7	TRISG6	—	—	TRISG3	TRISG2	TRISG1	TRISG0	xxxx
6620	PORTG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	RG15	RG14	RG13	RG12	—	—	RG9	RG8	RG7	RG6	—	—	RG3(2)	RG2(2)	RG1	RG0	xxxx
6630	LATG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	LATG15	LATG14	LATG13	LATG12	—	—	LATG9	LATG8	LATG7	LATG6	—	—	LATG3	LATG2	LATG1	LATG0	xxxx
6640	ODCG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ODCG15	ODCG14	ODCG13	ODCG12	—	—	ODCG9	ODCG8	ODCG7	ODCG6	—	—	ODCG3	ODCG2	ODCG1	ODCG0	xxxx
6650	CNPUG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPUG15	CNPUG14	CNPUG13	CNPUG12	—	—	CNPUG9	CNPUG8	CNPUG7	CNPUG6	—	—	CNPUG3	CNPUG2	CNPUG1	CNPUG0	xxxx
6660	CNPDG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNPDG15	CNPDG14	CNPDG13	CNPDG12	—	—	CNPDG9	CNPDG8	CNPDG7	CNPDG6	—	—	CNPDG3	CNPDG2	CNPDG1	CNPDG0	xxxx
6670	CNCONG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6680	CNENG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNIEG15	CNIEG14	CNIEG13	CNIEG12	—	—	CNIEG9	CNIEG8	CNIEG7	CNIEG6	—	—	CNIEG3	CNIEG2	CNIEG1	CNIEG0	xxxx
6690	CNSTATG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CNSTATG15	CNSTATG14	CNSTATG13	CNSTATG12	—	—	CNSTATG9	CNSTATG8	CNSTATG7	CNSTATG6	—	—	CNSTATG3	CNSTATG2	CNSTATG1	CNSTATG0	xxxx

Legend: x = Unknown value on Reset; — = Unimplemented, read as ‘0’; Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for more information.

2: This bit only implemented on devices without a USB module.

21.1 Control Registers

TABLE 21-1: PARALLEL MASTER PORT REGISTER MAP

Virtual Address (BF80_#)	Register Name[1]	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
7000	PMCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	ADRMUX<1:0>		PMPTTL	PTWREN	PTRDEN	CSF<1:0>		ALP	CS2P	CS1P	—	WRSP	RDSP	0000
7010	PMMODE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BUSY	IRQM<1:0>		INCM<1:0>		MODE16	MODE<1:0>		WAITB<1:0>		WAITM<3:0>				WAITE<1:0>		0000
7020	PMADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CS2	CS1	ADDR<13:0>														0000
7030	PMDOUT	31:16	DATAOUT<31:0>																0000
		15:0																	0000
7040	PMDIN	31:16	DATAIN<31:0>																0000
		15:0																	0000
7050	PMAEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PTEN<15:0>																0000
7060	PMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E	BFBF

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

© 2012-2016 Microchip Technology Inc.

REGISTER 22-6: ALRMDATE: ALARM DATE VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	MONTH10<3:0>				MONTH01<3:0>			
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	DAY10<1:0>				DAY01<3:0>			
7:0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	—	—	WDAY01<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as ‘0’

bit 23-20 **MONTH10<3:0>:** Binary Coded Decimal value of months bits, 10s place digits; contains a value of 0 or 1

bit 19-16 **MONTH01<3:0>:** Binary Coded Decimal value of months bits, 1s place digit; contains a value from 0 to 9

bit 15-12 **DAY10<3:0>:** Binary Coded Decimal value of days bits, 10s place digits; contains a value from 0 to 3

bit 11-8 **DAY01<3:0>:** Binary Coded Decimal value of days bits, 1s place digit; contains a value from 0 to 9

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **WDAY01<3:0>:** Binary Coded Decimal value of weekdays bits, 1s place digit; contains a value from 0 to 6

© 2012-2016 Microchip Technology Inc.

28.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 32. "Configuration"** (DS60001124) and **Section 33. "Programming and Diagnostics"** (DS60001129), which are available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX330/350/370/430/450/470 family of devices include several features intended to maximize application flexibility and reliability and minimize cost through elimination of external components. These are:

- Flexible device configuration
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

28.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- DEVCFG0: Device Configuration Word 0
- DEVCFG1: Device Configuration Word 1
- DEVCFG2: Device Configuration Word 2
- DEVCFG3: Device Configuration Word 3
- CFGCON: Configuration Control Register

In addition, the DEVID register (Register 28-6) provides device and revision information.

REGISTER 28-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 11-5 **Reserved:** Write '`1`'

bit 4-3 **ICESEL<1:0>:** In-Circuit Emulator/Debugger Communication Channel Select bits

`11` = PGEC1/PGED1 pair is used
`10` = PGEC2/PGED2 pair is used
`01` = PGEC3/PGED3 pair is used
`00` = Reserved

bit 2 **JTAGEN:** JTAG Enable bit[1]

`1` = JTAG is enabled
`0` = JTAG is disabled

bit 1-0 **DEBUG<1:0>:** Background Debugger Enable bits (forced to '`11`' if code-protect is enabled)

`1x` = Debugger is disabled
`0x` = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

© 2012-2016 Microchip Technology Inc.

TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS	**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature $0°C \le T_A \le +70°C$ for Commercial $-40°C \le T_A \le +85°C$ for Industrial $-40°C \le T_A \le +105°C$ for V-temp

Param. No.	Symb.	Characteristics	Min.	Typ.[1]	Max.	Units	Conditions
		Input Leakage Current (Note 3)					
DI50	I_{IL}	I/O Ports	—	—	±1	µA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$[2]	—	—	±1	µA	$V_{SS} \le V_{PIN} \le V_{DD}$
DI56		OSC1	—	—	±1	µA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT and HS modes
DI60a	I_{ICL}	**Input Low Injection Current**	0	—	-5[7,10]	mA	Pins with Analog functions. Exceptions: [N/A] = 0 mA max
							Digital 5V tolerant designated pins. Exceptions: [N/A] = 0 mA max
							Digital non-5V tolerant designated pins. Exceptions: [N/A] = 0 mA max

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **“Device Pin Tables”** section for the 5V tolerant pins.

6: The V_{IH} specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic “high” internally to the PIC32 device, provided that the external load does not exceed the minimum value of I_{CNPU}. For External “input” logic inputs that require a pull-up source, to guarantee the minimum V_{IH} of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

7: V_{IL} source < (V_{SS} - 0.3). Characterized but not tested.

8: V_{IH} source > (V_{DD} + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to V_{DD}, and therefore, cannot tolerate any “positive” input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., V_{IH} Source > (V_{DD} + 0.3) or V_{IL} source < (V_{SS} - 0.3)).

11: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, I_{ICL} = (((Vss - 0.3) - V_{IL} source) / Rs). If **Note 8**, I_{ICH} = ((I_{ICH} source - (V_{DD} + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (V_{SS} - 0.3) $\le V_{SOURCE} \le$ (V_{DD} + 0.3), injection current = `0`.

© 2012-2016 Microchip Technology Inc.

TABLE 31-18: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp					
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical[1]**	**Max.**	**Units**	**Conditions**	
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC **(Note 4)** ECPLL **(Note 3)**	
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT **(Note 4)**	
OS12			4	—	10	MHz	XTPLL **(Notes 3,4)**	
OS13			10	—	25	MHz	HS **(Note 4)**	
OS14			10	—	25	MHz	HSPLL **(Notes 3,4)**	
OS15			32	32.768	100	kHz	SOSC **(Note 4)**	
OS20	TOSC	TOSC = 1/FOSC = TCY **(Note 2)**	—	—	—	—	See parameter OS10 for FOSC value	
OS30	TOSL, TOSH	External Clock In (OSC1) High or Low Time	0.45 x TOSC	—	—	ns	EC **(Note 4)**	
OS31	TOSR, TOSF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x TOSC	ns	EC **(Note 4)**	
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and SOSC Clock Oscillator modes)	—	1024	—	TOSC	**(Note 4)**	
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	**(Note 4)**	
OS42	GM	External Oscillator Transconductance (Primary Oscillator only)	—	12	—	mA/V	VDD = 3.3V, TA = +25°C **(Note 4)**	

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

2: Instruction cycle period (TCY) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin.

3: PLL input requirements: 4 MHZ ≤ FPLLIN ≤ 5 MHZ (use PLL prescaler to reduce FOSC). This parameter is characterized, but tested at 10 MHz only at manufacturing.

4: This parameter is characterized, but not tested in manufacturing.

© 2012-2016 Microchip Technology Inc.

FIGURE 31-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

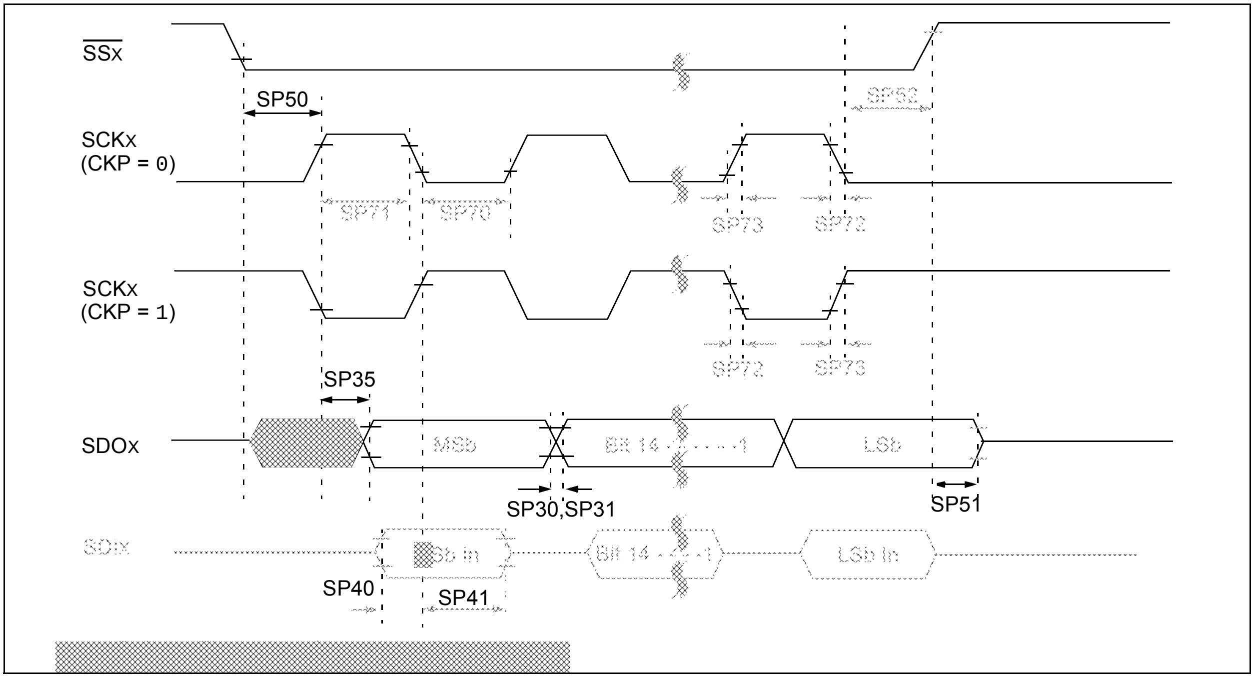


TABLE 31-31: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	TSCL	SCKx Input Low Time **(Note 3)**	TSCK/2	—	—	ns	—
SP71	TSCH	SCKx Input High Time **(Note 3)**	TSCK/2	—	—	ns	—
SP72	TSCF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TSCR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TDOF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TDOR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TSCH2DOV, TSCL2DOV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TSSL2SCH, TSSL2SCL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TSSH2DOZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance **(Note 3)**	5	—	25	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

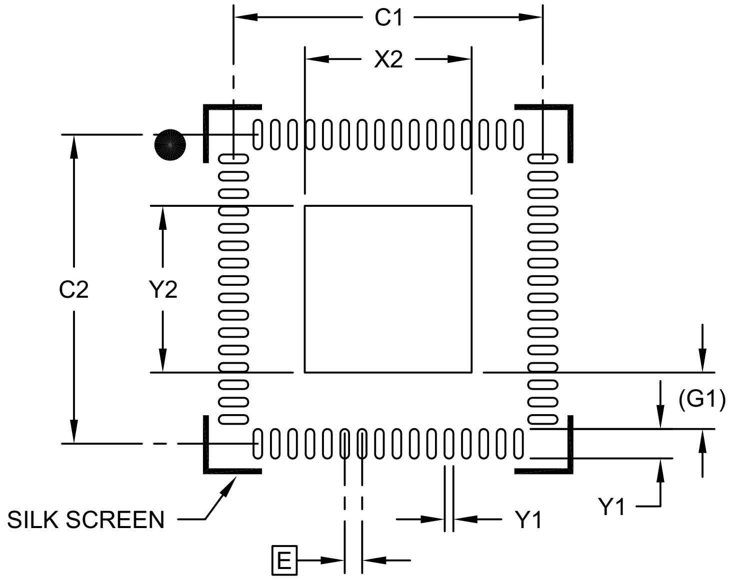
3: The minimum clock period for SCKx is 40 ns.

4: Assumes 50 pF load on all SPIx pins.

© 2012-2016 Microchip Technology Inc.

64-Lead Very Thin Plastic Quad Flat, No Lead Package (RG) - 9x9x1.0 mm Body [QFN] 4.7x4.7 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			4.80
Optional Center Pad Length	Y2			4.80
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.25
Contact Pad Length (X64)	Y1			0.85
Contact Pad to Center Pad (X64)	G1		1.625 REF	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2260A

© 2012-2016 Microchip Technology Inc.

Revision D (March 2015)

This revision includes the following updates, as listed in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 512 KB Flash and 128 KB SRAM) with Audio/Graphics/ Touch (HMI), USB, and Advanced Analog”	100 MHz and 120 MHz operation information was added. Pins 59 through 63 of the 64-pin QFN and TQFP pin diagrams were updated.
2.0 “Guidelines for Getting Started with 32-bit MCUs”	Added **2.8.1 “Crystal Oscillator Design Consideration”**.
12.0 “I/O Ports”	The Block Diagram of a Typical Multiplexed Port Structure was updated (see Figure 12-1).
21.0 “Parallel Master Port (PMP)”	The PMADDR: Parallel Port Address Register was updated (see Register 21-3).
31.0 “Electrical Characteristics”	Specifications for 120 MHz operation were added to the following tables: • Table 31-1: “Operating MIPS vs. Voltage” • Table 31-5: “DC Characteristics: Operating Current (IDD)” • Table 31-6: “DC Characteristics: Idle Current (IIDLE)” • Table 31-7: “DC Characteristics: Idle Current (IPD)” • Table 31-13: “DC Characteristics: Program Flash Memory Wait State” • Table 31-18: “External Clock Timing Requirements” The unit of measure for IIDLE Current parameters DC37a, DC37b, and DC37c were updated (see Table 31-6). Parameter D312 (TSET) was removed from the Comparator Specifications (see Table 31-14). Comparator Voltage Reference Specifications were added (see Table 31-15). Parameter OS10 (FOSC) in the External Clock Timing Requirements was updated (see Table 31-18). Parameter USB321 (VOL) in the OTG Electrical Specifications was updated (see Table 31-41).
32.0 “Packaging Information”	The 64-lead QFN package marking information was updated. The 124-lead VTLA package land pattern information was added.
“Product Identification System”	The Speed category was removed. The Example was updated. The MR package was updated. The RG package was added.